Intel - 5SGXEA4K3F35I3L Datasheet





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Details

Product Status	Obsolete
Number of LABs/CLBs	158500
Number of Logic Elements/Cells	420000
Total RAM Bits	37888000
Number of I/O	432
Number of Gates	-
Voltage - Supply	0.82V ~ 0.88V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1152-BBGA, FCBGA
Supplier Device Package	1152-FBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5sgxea4k3f35i3l

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

					(-,		
Transceiver Speed				Core Spe	ed Grade			
Grade	C1	C2, C2L	C3	C4	12, 12L	13, 13L	I 3YY	14
3		Yes	Yes	Yes		Yes	Yes (4)	Yes
GX channel—8.5 Gbps		165	165	165		163	163 17	165

Table 1. Stratix V GX and GS Commercial and Industrial Speed Grade Offering ^{(1), (2), (3)} (Part 2 of 2)

Notes to Table 1:

(1) C = Commercial temperature grade; I = Industrial temperature grade.

(2) Lower number refers to faster speed grade.

(3) C2L, I2L, and I3L speed grades are for low-power devices.

(4) I3YY speed grades can achieve up to 10.3125 Gbps.

Table 2 lists the industrial and commercial speed grades for the Stratix V GT devices. **Table 2. Stratix V GT Commercial and Industrial Speed Grade Offering** ⁽¹⁾, ⁽²⁾

Transaction Oracle Oracle	Core Speed Grade						
Transceiver Speed Grade	C1	C2	12	13			
2 GX channel—12.5 Gbps GT channel—28.05 Gbps	Yes	Yes	_	_			
3 GX channel—12.5 Gbps GT channel—25.78 Gbps	Yes	Yes	Yes	Yes			

Notes to Table 2:

(1) C = Commercial temperature grade; I = Industrial temperature grade.

(2) Lower number refers to faster speed grade.

Absolute Maximum Ratings

Absolute maximum ratings define the maximum operating conditions for Stratix V devices. The values are based on experiments conducted with the devices and theoretical modeling of breakdown and damage mechanisms. The functional operation of the device is not implied for these conditions.



Conditions other than those listed in Table 3 may cause permanent damage to the device. Additionally, device operation at the absolute maximum ratings for extended periods of time may have adverse effects on the device.

Table 3.	Absolute	Maximum	Ratings	for Stratix \	/ Devices	(Part 1 of 2)
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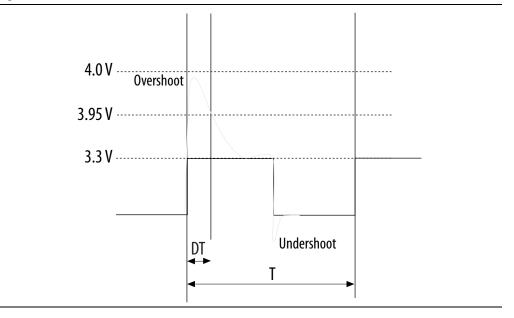
Symbol	Description	Minimum	Maximum	Unit
V _{CC}	Power supply for core voltage and periphery circuitry	-0.5	1.35	V
V _{CCPT}	Power supply for programmable power technology	-0.5	1.8	V
V _{CCPGM}	Power supply for configuration pins	-0.5	3.9	V
V _{CC_AUX}	Auxiliary supply for the programmable power technology	-0.5	3.4	V
V _{CCBAT}	Battery back-up power supply for design security volatile key register	-0.5	3.9	V
V _{CCPD}	I/O pre-driver power supply	-0.5	3.9	V
V _{CCIO}	I/O power supply	-0.5	3.9	V

Table 5 lists the maximum allowed input overshoot voltage and the duration of the overshoot voltage as a percentage of device lifetime. The maximum allowed overshoot duration is specified as a percentage of high time over the lifetime of the device. A DC signal is equivalent to 100% of the duty cycle. For example, a signal that overshoots to 3.95 V can be at 3.95 V for only ~21% over the lifetime of the device; for a device lifetime of 10 years, the overshoot duration amounts to ~2 years.

Table 5. Maximum Anoweu Overshout buring Hansitions									
Symbol	Description	Condition (V)	Overshoot Duration as % @ T _J = 100°C	Unit					
		3.8	100	%					
		3.85	64	%					
		3.9	36	%					
		3.95	21	%					
Vi (AC)	AC input voltage	4	12	%					
		4.05	7	%					
		4.1	4	%					
		4.15	2	%					
		4.2	1	%					

Table 5. Maximum Allowed Overshoot During Transitions

Figure 1. Stratix V Device Overshoot Duration



This section lists the functional operating limits for the AC and DC parameters for Stratix V devices. Table 6 lists the steady-state voltage and current values expected from Stratix V devices. Power supply ramps must all be strictly monotonic, without plateaus.

Table 6. Recommended Operating Conditions for Stratix V Devices (Part 1 of 2)

Symbol	Description	Condition	Min ⁽⁴⁾	Тур	Max ⁽⁴⁾	Unit
	Core voltage and periphery circuitry power supply (C1, C2, I2, and I3YY speed grades)	_	0.87	0.9	0.93	V
V _{CC}	Core voltage and periphery circuitry power supply (C2L, C3, C4, I2L, I3, I3L, and I4 speed grades) ⁽³⁾	_	0.82	0.85	0.88	V
V _{CCPT}	Power supply for programmable power technology	_	1.45	1.50	1.55	V
V _{CC_AUX}	Auxiliary supply for the programmable power technology	_	2.375	2.5	2.625	V
VI (1)	I/O pre-driver (3.0 V) power supply	_	2.85	3.0	3.15	V
V _{CCPD} ⁽¹⁾	I/O pre-driver (2.5 V) power supply	_	2.375	2.5	2.625	V
	I/O buffers (3.0 V) power supply		2.85	3.0	3.15	V
	I/O buffers (2.5 V) power supply	_	2.375	2.5	2.625	V
	I/O buffers (1.8 V) power supply		1.71	1.8	1.89	V
V _{CCIO}	I/O buffers (1.5 V) power supply	_	1.425	1.5	1.575	V
	I/O buffers (1.35 V) power supply	_	1.283	1.35	1.45	V
	I/O buffers (1.25 V) power supply	_	1.19	1.25	1.31	V
	I/O buffers (1.2 V) power supply	_	1.14	1.2	1.26	V
	Configuration pins (3.0 V) power supply	_	2.85	3.0	3.15	V
V _{CCPGM}	Configuration pins (2.5 V) power supply	_	2.375	2.5	2.625	V
	Configuration pins (1.8 V) power supply	_	1.71	1.8	1.89	V
V _{CCA_FPLL}	PLL analog voltage regulator power supply	_	2.375	2.5	2.625	V
V _{CCD_FPLL}	PLL digital voltage regulator power supply	_	1.45	1.5	1.55	V
V _{CCBAT} (2)	Battery back-up power supply (For design security volatile key register)	_	1.2	_	3.0	V
VI	DC input voltage	_	-0.5	_	3.6	V
V ₀	Output voltage	—	0	—	V _{CCIO}	V
т	Operating junction temperature	Commercial	0	—	85	°C
TJ	Operating junction temperature	Industrial	-40	_	100	°C

I/O Pin Leakage Current

Table 9 lists the Stratix V I/O pin leakage current specifications.

Table 9. I/	0 Pin Leakage	Current for Stratix 	/ Devices ⁽¹⁾
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Symbol	Description	Conditions	Min	Тур	Max	Unit
I _I	Input pin	$V_I = 0 V \text{ to } V_{CCIOMAX}$	-30	—	30	μA
I _{0Z}	Tri-stated I/O pin	$V_0 = 0 V$ to $V_{CCIOMAX}$	-30		30	μA

Note to Table 9:

(1) If $V_0 = V_{CCIO}$ to $V_{CCIOMax}$, 100 μ A of leakage current per I/O is expected.

Bus Hold Specifications

Table 10 lists the Stratix V device family bus hold specifications.

Table 10. Bus Hold Parameters for Stratix V Devices

							Va	CI0	-		-		
Parameter	Symbol	Conditions	1.2	2 V	1.	5 V	1.8	B V	2.	5 V	3.0	V	Unit
			Min	Max									
Low sustaining current	I _{SUSL}	V _{IN} > V _{IL} (maximum)	22.5	_	25.0	_	30.0	_	50.0	_	70.0	_	μA
High sustaining current	I _{SUSH}	V _{IN} < V _{IH} (minimum)	-22.5	_	-25.0	_	-30.0	_	-50.0	_	-70.0	_	μA
Low overdrive current	I _{odl}	$0V < V_{IN} < V_{CCIO}$	_	120	_	160	_	200	_	300	_	500	μA
High overdrive current	I _{odh}	$0V < V_{IN} < V_{CCIO}$		-120		-160	_	-200		-300	_	-500	μA
Bus-hold trip point	V _{trip}	_	0.45	0.95	0.50	1.00	0.68	1.07	0.70	1.70	0.80	2.00	V

On-Chip Termination (OCT) Specifications

If you enable OCT calibration, calibration is automatically performed at power-up for I/Os connected to the calibration block. Table 11 lists the Stratix V OCT termination calibration accuracy specifications.

Table 11. OCT Calibration Accuracy Specifications for Stratix V Devices ⁽¹⁾ (Part 1 of 2)

			Calibration Accuracy				
Symbol	Description	Conditions	C1	C2,I2	C3,I3, I3YY	C4,14	Unit
25-Ω R _S	Internal series termination with calibration (25- Ω setting)	V _{CCI0} = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	±15	±15	%

Symbol	Description	V _{CCIO} (V)	Typical	Unit
		3.0	0.189	
		2.5	0.208	
dR/dT	OCT variation with temperature without recalibration	1.8	0.266	%/°C
	without robalibration	1.5	0.273	
		1.2	0.317	

Table 13. OCT Variation after Power-Up Calibration for Stratix V Devices (Part 2 of 2)⁽¹⁾

Note to Table 13:

(1) Valid for a V_{CCIO} range of $\pm 5\%$ and a temperature range of 0° to 85°C.

Pin Capacitance

Table 14 lists the Stratix V device family pin capacitance.

Table 14. Pin Capacitance for Stratix V Devices

Symbol	Description	Value	Unit
C _{IOTB}	Input capacitance on the top and bottom I/O pins	6	pF
C _{IOLR}	Input capacitance on the left and right I/O pins	6	pF
C _{OUTFB}	Input capacitance on dual-purpose clock output and feedback pins	6	рF

Hot Socketing

Table 15 lists the hot socketing specifications for Stratix V devices.

Table 15.	Hot Socketing Specifications for Stratix V Devices
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Symbol	Description	Maximum
I _{IOPIN (DC)}	DC current per I/O pin	300 μA
I _{IOPIN (AC)}	AC current per I/O pin	8 mA ⁽¹⁾
I _{XCVR-TX (DC)}	DC current per transceiver transmitter pin	100 mA
I _{XCVR-RX (DC)}	DC current per transceiver receiver pin	50 mA

Note to Table 15:

(1) The I/O ramp rate is 10 ns or more. For ramp rates faster than 10 ns, $|I_{10PIN}| = C dv/dt$, in which C is the I/O pin capacitance and dv/dt is the slew rate.

I/O		V _{ccio} (V)		V _{DIF(}	_{DC)} (V)		V _{X(AC)} (V)		V _{CM(DC)} (V)			V _{DIF(AC)} (V)	
Standard	Min	Тур	Max	Min	Max	Min	Тур	Max	Min	Тур	Max	Min	Max
HSTL-12 Class I, II	1.14	1.2	1.26	0.16	V _{CCI0} + 0.3	_	0.5* V _{CCI0}	_	0.4* V _{CCI0}	0.5* V _{CCIO}	0.6* V _{CCIO}	0.3	V _{CCI0} + 0.48
HSUL-12	1.14	1.2	1.3	0.26	0.26	0.5*V _{CCI0} - 0.12	0.5* V _{CCIO}	0.5*V _{CCI0} + 0.12	0.4* V _{CCIO}	0.5* V _{CCIO}	0.6* V _{CCIO}	0.44	0.44

Table 21. Differential HSTL and HSUL I/O Standards for Stratix V Devices (Part 2 of 2)

Table 22. Differential I/O Standard Specifications for Stratix V Devices (7)

I/O	Vc	_{cio} (V)	(10)		V _{ID} (mV) ⁽⁸⁾			V _{ICM(DC)} (V)		Vo	_D (V) (5)	V _{осм} (V) <i>(6)</i>		
Standard	Min	Тур	Max	Min	Condition	Max	Min	Condition	Max	Min	Тур	Max	Min	Тур	Max
PCML	ML Transmitter, receiver, and input reference clock pins of the high-speed transceivers use the PCML I/O standard. For transmitter, receiver, and reference clock I/O pin specifications, refer to Table 23 on page 18.														
2.5 V		V _{CM} =	_	0.05	D _{MAX} ≤ 700 Mbps	1.8	0.247	_	0.6	1.125	1.25	1.375			
LVDS ⁽¹⁾	2.375	2.0	2.025	100	1.25 V	_	1.05	D _{MAX} > 700 Mbps	1.55	0.247	_	0.6	1.125	1.25	1.375
BLVDS (5)	2.375	2.5	2.625	100	_	_		—	_	_	_		_		
RSDS (HIO) ⁽²⁾	2.375	2.5	2.625	100	V _{CM} = 1.25 V	_	0.3	—	1.4	0.1	0.2	0.6	0.5	1.2	1.4
Mini- LVDS (HIO) ⁽³⁾	2.375	2.5	2.625	200		600	0.4	_	1.325	0.25	_	0.6	1	1.2	1.4
LVPECL (4			_	300		_	0.6	D _{MAX} ≤ 700 Mbps	1.8		_	_			
), (9)		_		300	_	_	1	D _{MAX} > 700 Mbps	1.6		_	_			—

Notes to Table 22:

(1) For optimized LVDS receiver performance, the receiver voltage input range must be between 1.0 V to 1.6 V for data rates above 700 Mbps, and 0 V to 1.85 V for data rates below 700 Mbps.

(2) For optimized RSDS receiver performance, the receiver voltage input range must be between 0.25 V to 1.45 V.

(3) For optimized Mini-LVDS receiver performance, the receiver voltage input range must be between 0.3 V to 1.425 V.

- (4) For optimized LVPECL receiver performance, the receiver voltage input range must be between 0.85 V to 1.75 V for data rate above 700 Mbps and 0.45 V to 1.95 V for data rate below 700 Mbps.
- (5) There are no fixed V_{ICM} , V_{OD} , and V_{OCM} specifications for BLVDS. They depend on the system topology.
- (6) RL range: $90 \le RL \le 110 \Omega$.
- (7) The 1.4-V and 1.5-V PCML transceiver I/O standard specifications are described in "Transceiver Performance Specifications" on page 18.
- (8) The minimum VID value is applicable over the entire common mode range, VCM.
- (9) LVPECL is only supported on dedicated clock input pins.
- (10) Differential inputs are powered by VCCPD which requires 2.5 V.

Power Consumption

Altera offers two ways to estimate power consumption for a design—the Excel-based Early Power Estimator and the Quartus[®] II PowerPlay Power Analyzer feature.

Table 23. Transceiver Specifications for Stratix V GX and GS Devices ⁽¹⁾ (Part 6 of 7)

Symbol/	Conditions	Trai	isceive Grade	r Speed 1	Trar	isceive Grade	r Speed 2	Tran	isceive Grade	er Speed e 3	Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
Inter-transceiver block transmitter channel-to- channel skew	xN PMA bonded mode			500	_		500	_		500	ps
CMU PLL											
Supported Data Range	_	600		12500	600	_	12500	600	_	8500/ 10312.5 (24)	Mbps
t _{pll_powerdown} ⁽¹⁵⁾	_	1		—	1	—	—	1	—	—	μs
t _{pll_lock} (16)	_		_	10	—	_	10	—	—	10	μs
ATX PLL	1										
	VCO post-divider L=2	8000		14100	8000	_	12500	8000	_	8500/ 10312.5 (24)	Mbps
Current and Date	L=4	4000	_	7050	4000	_	6600	4000	—	6600	Mbps
Supported Data Rate Range	L=8	2000	_	3525	2000	_	3300	2000	_	3300	Mbps
	L=8, Local/Central Clock Divider =2	1000	_	1762.5	1000		1762.5	1000		1762.5	Mbps
t _{pll_powerdown} (15)	_	1		_	1			1	—	_	μs
t _{pll_lock} ⁽¹⁶⁾	—			10	—	—	10	—	—	10	μs
fPLL	•			•					•		
Supported Data Range	_	600	_	3250/ 3125 ⁽²⁵⁾	600	_	3250/ 3125 ⁽²⁵⁾	600	_	3250/ 3125 ⁽²⁵⁾	Mbps
t _{pll_powerdown} ⁽¹⁵⁾	_	1	_	_	1	_	—	1	—	—	μs

Table 27 shows the V_{OD} settings for the GX channel.

Symbol	V _{op} Setting	V _{op} Value (mV)	V _{op} Setting	V _{op} Value (mV)
	0 (1)	0	32	640
	1 ⁽¹⁾	20	33	660
	2 (1)	40	34	680
	3 (1)	60	35	700
	4 (1)	80	36	720
	5 (1)	100	37	740
	6	120	38	760
	7	140	39	780
	8	160	40	800
	9	180	41	820
	10	200	42	840
	11	220	43	860
	12	240	44	880
	13	260	45	900
	14	280	46	920
V _{op} differential peak to peak	15	300	47	940
typical ⁽³⁾	16	320	48	960
	17	340	49	980
	18	360	50	1000
	19	380	51	1020
	20	400	52	1040
	21	420	53	1060
	22	440	54	1080
	23	460	55	1100
	24	480	56	1120
	25	500	57	1140
	26	520	58	1160
	27	540	59	1180
	28	560	60	1200
	29	580	61	1220
	30	600	62	1240
	31	620	63	1260

Table 27. Typical V_{0D} Setting for GX Channel, TX Termination = 100 $\Omega^{\left(2\right)}$

Note to Table 27:

(1) If TX termination resistance = 100Ω , this VOD setting is illegal.

(2) The tolerance is +/-20% for all VOD settings except for settings 2 and below.

(3) Refer to Figure 2.



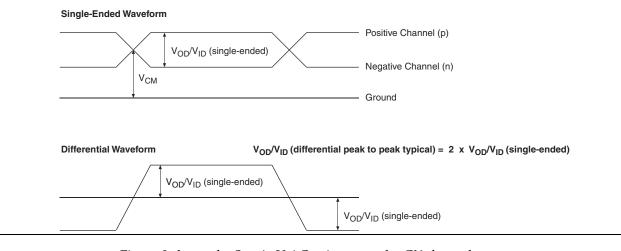


Figure 3 shows the Stratix V AC gain curves for GX channels.

Figure 3. AC Gain Curves for GX Channels (full bandwidth)

Stratix V GT devices contain both GX and GT channels. All transceiver specifications for the GX channels not listed in Table 28 are the same as those listed in Table 23.

Table 28 lists the Stratix V GT transceiver specifications.

Table 28. Transceiver Specifications for Stratix V GT Devices (Part 5 of 5) (Fransceiver Specifications for Stratix V GT Devices (Part 5 of 5) ⁽¹⁾
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Symbol/ Description	Conditions		Transceivei peed Grade		S	Unit		
Description		Min	Тур	Max	Min	Тур	Max	
t _{pll_lock} ⁽¹⁴⁾	—	—	_	10	—	—	10	μs

Notes to Table 28:

- (1) Speed grades shown refer to the PMA Speed Grade in the device ordering code. The maximum data rate could be restricted by the Core/PCS speed grade. Contact your Altera Sales Representative for the maximum data rate specifications in each speed grade combination offered. For more information about device ordering codes, refer to the Stratix V Device Overview.
- (2) The reference clock common mode voltage is equal to the VCCR_GXB power supply level.
- (3) The device cannot tolerate prolonged operation at this absolute maximum.
- (4) The differential eye opening specification at the receiver input pins assumes that receiver equalization is disabled. If you enable receiver equalization, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level.
- (5) Refer to Figure 5 for the GT channel AC gain curves. The total effective AC gain is the AC gain minus the DC gain.
- (6) Refer to Figure 6 for the GT channel DC gain curves.
- (7) CFP2 optical modules require the host interface to have the receiver data pins differentially terminated with 100 Ω. The internal OCT feature is available after the Stratix V FPGA configuration is completed. Altera recommends that FPGA configuration is completed before inserting the optical module. Otherwise, minimize unnecessary removal and insertion with unconfigured devices.
- (8) Specifications for this parameter are the same as for Stratix V GX and GS devices. See Table 23 for specifications.
- (9) t_{1 TR} is the time required for the receive CDR to lock to the input reference clock frequency after coming out of reset.
- (10) t_{LTD} is time required for the receiver CDR to start recovering valid data after the rx is lockedtodata signal goes high.
- (11) t_{LTD_manual} is the time required for the receiver CDR to start recovering valid data after the rx_is_lockedtodata signal goes high when the CDR is functioning in the manual mode.
- (12) t_{LTR_LTD_manual} is the time the receiver CDR must be kept in lock to reference (LTR) mode after the rx_is_lockedtoref signal goes high when the CDR is functioning in the manual mode.
- (13) tpll_powerdown is the PLL powerdown minimum pulse width.
- (14) tpll lock is the time required for the transmitter CMU/ATX PLL to lock to the input reference clock frequency after coming out of reset.
- (15) To calculate the REFCLK rms phase jitter requirement for PCle at reference clock frequencies other than 100 MHz, use the following formula: REFCLK rms phase jitter at f(MHz) = REFCLK rms phase jitter at 100 MHz × 100/f.
- (16) The maximum peak to peak differential input voltage V_{ID} after device configuration is equal to 4 × (absolute V_{MAX} for receiver pin V_{ICM}).
- (17) For ES devices, RREF is 2000 $\Omega \pm 1\%$.
- (18) To calculate the REFCLK phase noise requirement at frequencies other than 622 MHz, use the following formula: REFCLK phase noise at f(MHz) = REFCLK phase noise at 622 MHz + 20*log(f/622).
- (19) SFP/+ optical modules require the host interface to have RD+/- differentially terminated with 100 Ω. The internal OCT feature is available after the Stratix V FPGA configuration is completed. Altera recommends that FPGA configuration is completed before inserting the optical module. Otherwise, minimize unnecessary removal and insertion with unconfigured devices.
- (20) Refer to Figure 4.
- (21) For oversampling design to support data rates less than the minimum specification, the CDR needs to be in LTR mode only.
- (22) This supply follows VCCR_GXB for both GX and GT channels.
- (23) When you use fPLL as a TXPLL of the transceiver.

Figure 4 shows the differential transmitter output waveform.



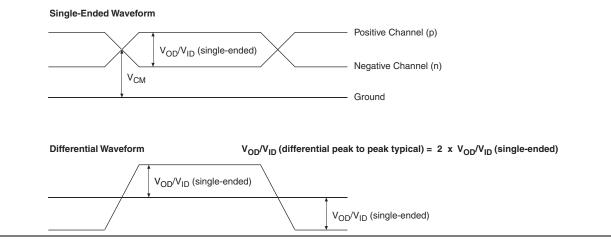


Figure 5 shows the Stratix V AC gain curves for GT channels.

Figure 5. AC Gain Curves for GT Channels

- XFI
- ASI
- HiGig/HiGig+
- HiGig2/HiGig2+
- Serial Data Converter (SDC)
- GPON
- SDI
- SONET
- Fibre Channel (FC)
- PCIe
- QPI
- SFF-8431

Download the Stratix V Characterization Report Tool to view the characterization report summary for these protocols.

Core Performance Specifications

This section describes the clock tree, phase-locked loop (PLL), digital signal processing (DSP), memory blocks, configuration, and JTAG specifications.

Clock Tree Specifications

Table 30 lists the clock tree specifications for Stratix V devices.

Table 30. Clock Tree Performance for Stratix V Devices (1)

		Performance		
Symbol	C1, C2, C2L, I2, and I2L	C3, I3, I3L, and I3YY	C4, I4	Unit
Global and Regional Clock	717	650	580	MHz
Periphery Clock	550	500	500	MHz

Note to Table 30:

(1) The Stratix V ES devices are limited to 600 MHz core clock tree performance.

PLL Specifications

Table 31 lists the Stratix V PLL specifications when operating in both the commercial junction temperature range (0° to 85° C) and the industrial junction temperature range (-40° to 100° C).

Table 31. PLL Specifications for Stratix V Devices (Part 1 of 3)

Symbol	Parameter	Min	Тур	Max	Unit
	Input clock frequency (C1, C2, C2L, I2, and I2L speed grades)	5	_	800 (1)	MHz
f _{IN}	Input clock frequency (C3, I3, I3L, and I3YY speed grades)	5	_	800 (1)	MHz
	Input clock frequency (C4, I4 speed grades)	5	_	650 ⁽¹⁾	MHz
f _{INPFD}	Input frequency to the PFD	5	—	325	MHz
f _{finpfd}	Fractional Input clock frequency to the PFD	50	_	160	MHz
	PLL VCO operating range (C1, C2, C2L, I2, I2L speed grades)	600	_	1600	MHz
f _{VCO}	PLL VCO operating range (C3, I3, I3L, I3YY speed grades)	600	_	1600	MHz
	PLL VCO operating range (C4, I4 speed grades)	600	—	1300	MHz
t _{einduty}	Input clock or external feedback clock input duty cycle	40		60	%
	Output frequency for an internal global or regional clock (C1, C2, C2L, I2, I2L speed grades)	—	_	717 ⁽²⁾	MHz
f _{OUT}	Output frequency for an internal global or regional clock (C3, I3, I3L speed grades)	_	_	650 ⁽²⁾	MHz
	Output frequency for an internal global or regional clock (C4, I4 speed grades)	_	_	580 ⁽²⁾	MHz
	Output frequency for an external clock output (C1, C2, C2L, I2, I2L speed grades)	_	_	800 (2)	MHz
f _{out_ext}	Output frequency for an external clock output (C3, I3, I3L speed grades)	_	_	667 ⁽²⁾	MHz
	Output frequency for an external clock output (C4, I4 speed grades)	_	_	553 ⁽²⁾	MHz
t _{outduty}	Duty cycle for a dedicated external clock output (when set to 50%)	45	50	55	%
t _{FCOMP}	External feedback clock compensation time	_	—	10	ns
f _{dyconfigclk}	Dynamic Configuration Clock used for <code>mgmt_clk</code> and <code>scanclk</code>	_	_	100	MHz
t _{LOCK}	Time required to lock from the end-of-device configuration or deassertion of areset	_	_	1	ms
t _{olock}	Time required to lock dynamically (after switchover or reconfiguring any non-post-scale counters/delays)	_	_	1	ms
	PLL closed-loop low bandwidth		0.3	—	MHz
f _{CLBW}	PLL closed-loop medium bandwidth	_	1.5		MHz
	PLL closed-loop high bandwidth (7)		4	—	MHz
t _{PLL_PSERR}	Accuracy of PLL phase shift			±50	ps
t _{areset}	Minimum pulse width on the areset signal	10	_		ns

	Peformance							
Mode	C1	C2, C2L	12, 12L	C3	13, 13L, 13YY	C4	14	Unit
Modes using Three DSPs								
One complex 18 x 25	425	425	415	340	340	275	265	MHz
Modes using Four DSPs								
One complex 27 x 27	465	465	465	380	380	300	290	MHz

Table 32. Block Performance Specifications for Stratix V DSP Devices (Part 2 of 2)

Memory Block Specifications

Table 33 lists the Stratix V memory block specifications.

Table 33. Memory Block Performance Specifications for Stratix V Devices (1), (2) (Part 1 of 2)

		Resources Used		Performance							
Memory	Mode	ALUTS	Memory	C1	C2, C2L	C3	C4	12, 12L	13, 13L, 13YY	14	Unit
	Single port, all supported widths	0	1	450	450	400	315	450	400	315	MHz
MLAB	Simple dual-port, x32/x64 depth	0	1	450	450	400	315	450	400	315	MHz
IVILAD	Simple dual-port, x16 depth ⁽³⁾	0	1	675	675	533	400	675	533	400	MHz
	ROM, all supported widths	0	1	600	600	500	450	600	500	450	MHz

Gumbal	Oenditione		C1		C2,	C2L, I	2, I2L	C3,	13, I3L	., I3YY		C4,I	4	11
Symbol	Conditions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
	SERDES factor J = 3 to 10	(6)	_	(8)	(6)	_	(8)	(6)		(8)	(6)		(8)	Mbps
f _{HSDR} (data rate)	SERDES factor J = 2, uses DDR Registers	(6)		(7)	(6)	_	(7)	(6)		(7)	(6)		(7)	Mbps
	SERDES factor J = 1, uses SDR Register	(6)	_	(7)	(6)	_	(7)	(6)		(7)	(6)		(7)	Mbps
DPA Mode														
DPA run length	—			1000 0		_	1000 0		_	1000 0		_	1000 0	UI
Soft CDR mode)													
Soft-CDR PPM tolerance	_	_	_	300	_	—	300	_		300	_		300	± PPM
Non DPA Mode	•	•		-		-		•		-			-	-
Sampling Window	_			300			300			300			300	ps

Table 36. High-Speed I/O Specifications for Stratix V Devices ^{(1), (2)} (Part 4 of 4)

Notes to Table 36:

(1) When J = 3 to 10, use the serializer/deserializer (SERDES) block.

(2) When J = 1 or 2, bypass the SERDES block.

(3) This only applies to DPA and soft-CDR modes.

(4) Clock Boost Factor (W) is the ratio between the input data rate to the input clock rate.

(5) This is achieved by using the **LVDS** clock network.

(6) The minimum specification depends on the clock source (for example, the PLL and clock pin) and the clock routing resource (global, regional, or local) that you use. The I/O differential buffer and input register do not have a minimum toggle rate.

(7) The maximum ideal frequency is the SERDES factor (J) x the PLL maximum output frequency (fOUT) provided you can close the design timing and the signal integrity simulation is clean.

(8) You can estimate the achievable maximum data rate for non-DPA mode by performing link timing closure analysis. You must consider the board skew margin, transmitter delay margin, and receiver sampling margin to determine the maximum data rate supported.

(9) If the receiver with DPA enabled and transmitter are using shared PLLs, the minimum data rate is 150 Mbps.

(10) You must calculate the leftover timing margin in the receiver by performing link timing closure analysis. You must consider the board skew margin, transmitter channel-to-channel skew, and receiver sampling margin to determine leftover timing margin.

(11) The F_{MAX} specification is based on the fast clock used for serial data. The interface F_{MAX} is also dependent on the parallel clock domain which is design-dependent and requires timing analysis.

(12) Stratix V RX LVDS will need DPA. For Stratix V TX LVDS, the receiver side component must have DPA.

(13) Stratix V LVDS serialization and de-serialization factor needs to be x4 and above.

(14) Requires package skew compensation with PCB trace length.

(15) Do not mix single-ended I/O buffer within LVDS I/O bank.

(16) Chip-to-chip communication only with a maximum load of 5 pF.

(17) When using True LVDS RX channels for emulated LVDS TX channel, only serialization factors 1 and 2 are supported.

Speed Grade	Min	Max	Unit
C4,I4	8	16	ps

Table 40. DQS Phase Offset Delay Per Setting for Stratix V Devices ^{(1), (2)} (Part 2 of 2)

Notes to Table 40:

(1) The typical value equals the average of the minimum and maximum values.

(2) The delay settings are linear with a cumulative delay variation of 40 ps for all speed grades. For example, when using a -2 speed grade and applying a 10-phase offset setting to a 90° phase shift at 400 MHz, the expected average cumulative delay is [625 ps + (10 × 10 ps) ± 20 ps] = 725 ps ± 20 ps.

Table 41 lists the DQS phase shift error for Stratix V devices.

Table 41. DQS Phase Shift Error Specification for DLL-Delayed Clock (t_{DQS_PSERR}) for Stratix V Devices ⁽¹⁾

Number of DQS Delay Buffers	C1	C2, C2L, I2, I2L	C3, I3, I3L, I3YY	C4,14	Unit
1	28	28	30	32	ps
2	56	56	60	64	ps
3	84	84	90	96	ps
4	112	112	120	128	ps

Notes to Table 41:

(1) This error specification is the absolute maximum and minimum error. For example, skew on three DQS delay buffers in a -2 speed grade is ± 78 ps or ± 39 ps.

Table 42 lists the memory output clock jitter specifications for Stratix V devices.

Clock Network	Parameter	Parameter Symbol				C2, C2L, I2, I2L		C3, I3, I3L, I3YY		C4,14	
		-	Min	Max	Min	Max	Min	Max	Min	Max	
	Clock period jitter	t _{JIT(per)}	-50	50	-50	50	-55	55	-55	55	ps
Regional	Cycle-to-cycle period jitter	$t_{\rm JIT(cc)}$	-100	100	-100	100	-110	110	-110	110	ps
	Duty cycle jitter	$t_{JIT(duty)}$	-50	50	-50	50	-82.5	82.5	-82.5	82.5	ps
	Clock period jitter	t _{JIT(per)}	-75	75	-75	75	-82.5	82.5	-82.5	82.5	ps
Global	Cycle-to-cycle period jitter	$t_{\text{JIT(cc)}}$	-150	150	-150	150	-165	165	-165	165	ps
	Duty cycle jitter	$t_{JIT(duty)}$	-75	75	-75	75	-90	90	-90	90	ps

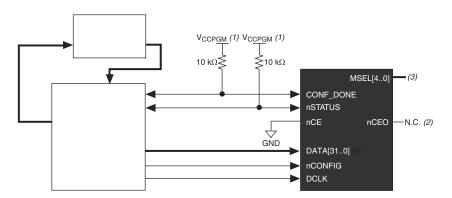
Configuration Scheme	Decompression	Design Security	DCLK-to-DATA[] Ratio
	Disabled	Disabled	1
FPP ×32	Disabled	Enabled	4
FFF X02	Enabled	Disabled	8
	Enabled	Enabled	8

Note to Table 49:

(1) Depending on the DCLK-to-DATA [] ratio, the host must send a DCLK frequency that is r times the data rate in bytes per second (Bps), or words per second (Wps). For example, in FPP ×16 when the DCLK-to-DATA [] ratio is 2, the DCLK frequency must be 2 times the data rate in Wps. Stratix V devices use the additional clock cycles to decrypt and decompress the configuration data.

Figure 11 shows the configuration interface connections between the Stratix V device and a MAX II or MAX V device for single device configuration.

Figure 11. Single Device FPP Configuration Using an External Host



Notes to Figure 11:

- (1) Connect the resistor to a supply that provides an acceptable input signal for the Stratix V device. V_{CCPGM} must be high enough to meet the V_{IH} specification of the I/O on the device and the external host. Altera recommends powering up all configuration system I/Os with V_{CCPGM} .
- (2) You can leave the nCEO pin unconnected or use it as a user I/O pin when it does not feed another device's nCE pin.
- (3) The MSEL pin settings vary for different data width, configuration voltage standards, and POR delay. To connect MSEL, refer to the MSEL Pin Settings section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (4) If you use FPP ×8, use DATA [7..0]. If you use FPP ×16, use DATA [15..0].

IF the DCLK-to-DATA[] ratio is greater than 1, at the end of configuration, you can only stop the DCLK (DCLK-to-DATA[] ratio – 1) clock cycles after the last data is latched into the Stratix V device.

Table 54 lists the PS configuration timing parameters for Stratix V devices.

Table 54. PS Timing Parameters for Stratix V Devices

Symbol	Parameter	Minimum	Maximum	Units
t _{CF2CD}	nCONFIG low to CONF_DONE low	—	600	ns
t _{CF2ST0}	nCONFIG low to nSTATUS low	—	600	ns
t _{CFG}	nCONFIG low pulse width	2	—	μS
t _{status}	nSTATUS low pulse width	268	1,506 ⁽¹⁾	μS
t _{CF2ST1}	nCONFIG high to nSTATUS high	—	1,506 ⁽²⁾	μS
t _{CF2CK} (5)	nCONFIG high to first rising edge on DCLK	1,506	—	μS
t _{ST2CK} ⁽⁵⁾	nSTATUS high to first rising edge of DCLK	2	—	μS
t _{DSU}	DATA[] setup time before rising edge on DCLK	5.5	—	ns
t _{DH}	DATA[] hold time after rising edge on DCLK	0	—	ns
t _{CH}	DCLK high time	$0.45\times 1/f_{MAX}$	—	S
t _{CL}	DCLK low time	$0.45\times 1/f_{MAX}$	—	S
t _{CLK}	DCLK period	1/f _{MAX}	—	S
f _{MAX}	DCLK frequency	—	125	MHz
t _{CD2UM}	CONF_DONE high to user mode (3)	175	437	μS
t _{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	_	_
t _{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	t_{CD2CU} + (8576 × CLKUSR period) ⁽⁴⁾	_	_

Notes to Table 54:

(1) This value is applicable if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.

(2) This value is applicable if you do not delay configuration by externally holding the nSTATUS low.

(3) The minimum and maximum numbers apply only if you choose the internal oscillator as the clock source for initializing the device.

(4) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the "Initialization" section.

(5) If nSTATUS is monitored, follow the t_{ST2CK} specification. If nSTATUS is not monitored, follow the t_{CF2CK} specification.

Initialization

Table 55 lists the initialization clock source option, the applicable configuration schemes, and the maximum frequency.

Table 55. Initialization Clock Source Option and the Maximu	m Frequency
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Initialization Clock Source	Configuration Schemes	Maximum Frequency	Minimum Number of Clock Cycles ⁽¹⁾
Internal Oscillator	AS, PS, FPP	12.5 MHz	
CLKUSR	AS, PS, FPP ⁽²⁾	125 MHz	8576
DCLK	PS, FPP	125 MHz	

Notes to Table 55:

(1) The minimum number of clock cycles required for device initialization.

(2) To enable CLKUSR as the initialization clock source, turn on the Enable user-supplied start-up clock (CLKUSR) option in the Quartus II software from the General panel of the Device and Pin Options dialog box.

Remote System Upgrades

Table 56 lists the timing parameter specifications for the remote system upgrade circuitry.

Table 56. Remote System Upgrade Circuitry Timing Specifications	Table 56.	Remote System	Upgrade Circuitry	y Timing S	Specifications
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Parameter	Minimum	Maximum	Unit		
t _{RU_nCONFIG} ⁽¹⁾	250	—	ns		
t _{RU_nRSTIMER} ⁽²⁾	250	—	ns		

Notes to Table 56:

- (1) This is equivalent to strobing the reconfiguration input of the ALTREMOTE_UPDATE megafunction high for the minimum timing specification. For more information, refer to the Remote System Upgrade State Machine section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (2) This is equivalent to strobing the reset_timer input of the ALTREMOTE_UPDATE megafunction high for the minimum timing specification. For more information, refer to the User Watchdog Timer section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.

User Watchdog Internal Circuitry Timing Specification

Table 57 lists the operating range of the 12.5-MHz internal oscillator.

Table 57. 12.5-MHz Internal Oscillator Specifications

Minimum	Typical	Maximum	Units		
5.3	7.9	12.5	MHz		

I/O Timing

Altera offers two ways to determine I/O timing—the Excel-based I/O Timing and the Quartus II Timing Analyzer.

Excel-based I/O timing provides pin timing performance for each device density and speed grade. The data is typically used prior to designing the FPGA to get an estimate of the timing budget as part of the link timing analysis. The Quartus II Timing Analyzer provides a more accurate and precise I/O timing data based on the specifics of the design after you complete place-and-route.

 You can download the Excel-based I/O Timing spreadsheet from the Stratix V Devices Documentation web page.

Programmable IOE Delay

Table 58 lists the Stratix V IOE programmable delay settings.

Table 58. IOE Programmable Delay for Stratix V Devices (Part 1 of 2)

Deremeter	Available	ilable Offset	Model	Slow Model								
Parameter (1)	Settings		Industrial	Commercial	C1	C2	C3	C4	12	13, 13YY	14	Unit
D1	64	0	0.464	0.493	0.838	0.838	0.924	1.011	0.844	0.921	1.006	ns
D2	32	0	0.230	0.244	0.415	0.415	0.459	0.503	0.417	0.456	0.500	ns

Table 60. Glossary (Part 2 of 4)

Letter	Subject	Definitions			
G					
Н	_	_			
Ι					
J	J JTAG Timing Specifications	High-speed I/O block—Deserialization factor (width of parallel data bus). JTAG Timing Specifications: TMS TDI t_{JCP} t_{JCH} t_{JCH} t_{JPCO} t_{JPCO} t_{JPXZ} TDO t_{JPXZ} t_{JPXZ}			
K L M N O	_	_			
Ρ	PLL Specifications	Diagram of PLL Specifications (1)			
Q		_			
	1	Receiver differential input discrete resistor (external to the Stratix V device).			